

FORM PTO-1449 (Modified)		U.S. Department of Commerce Patent and Trademark Office	Attorney Docket No.: COOL-00601	Serial No.: 10/699,505
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary) (37 CFR § 1.98(b))		Applicants.: Girish Upadhyay et al.		
		Filing Date.: October 30, 2003		Group Art Unit.: 3743
OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)				
	AA	Yongendra Joshi, "Heat out of small packages", December 2001, Mechanical Engineer, pages 56-58.		
	AB	Snezana Konecni et al., "Convection Cooling of Microelectronic Chips", 1992, InterSociety Conference on Thermal Phenomena, pages 138-144.		
MAR 9 2004 RENT A TRADEMA	AC	Michael B. Kleiner et al., "High Performance Forced Air Cooling Scheme Employing Microchannel Heat Exchangers", 1995, IEEE Transactions on Components, Packaging, and Manufacturing Technology-Part A, Vol. 18, No. 4, pages 795-804.		
	AD	Jerry K. Keska Ph. D. et al., "An Experimental Study on an Enhanced Microchannel Heat Sink for Microelectronics Applications", EEP-Vol. 26-2, Advances in Electronic Packaging, 1999, Vol. 2, pages 1235-1259.		
	AE	A. J. Arnold et al., "Heat Sink Design for Cooling Modules in a Forced Air Environment", IBM Technical Disclosure Bulletin, Vol. 22, No. 6, November 1979, pages 2297-2298.		
	AF	"Forced Boiling Cooling System with Jet Enhancement for Critical Heat Flux Extension", IBM Technical Disclosure Bulletin, Vol. 39, No. 10, October 1996, page 143.		
	AG	"Self-Contained Active Heat Dissipation Device", IBM Technical Disclosure Bulletin Vol. 39, No. 04, April 1996, pages 115-116.		
	AH	"Pin Fin Array Heat Pipe Apparatus", IBM Technical Disclosure Bulletin, Vol. 37, No. 09, September 1994, page 171.		
	AI	Mali Mahalingam, <u>Thermal Management in Semiconductor Device Packaging</u> , 1985, Proceedings of the IEEE, Vol. 73, No. 9, September 1985, pages 1396-1404.		
	AJ	Roy W. Knight et al., <u>Optimal Thermal Design of Air cooled Forced Convection finned Heat Sinks - Experimental Verification</u> , October 1992, IEEE Transactions on Components, Hybrids, and Manufacturing Technology, Vol. 15, No. 5 pages 754-760.		
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Examiner: <i>Amritpal Singh</i>		Date Considered: <i>7/28/05</i>		
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.				